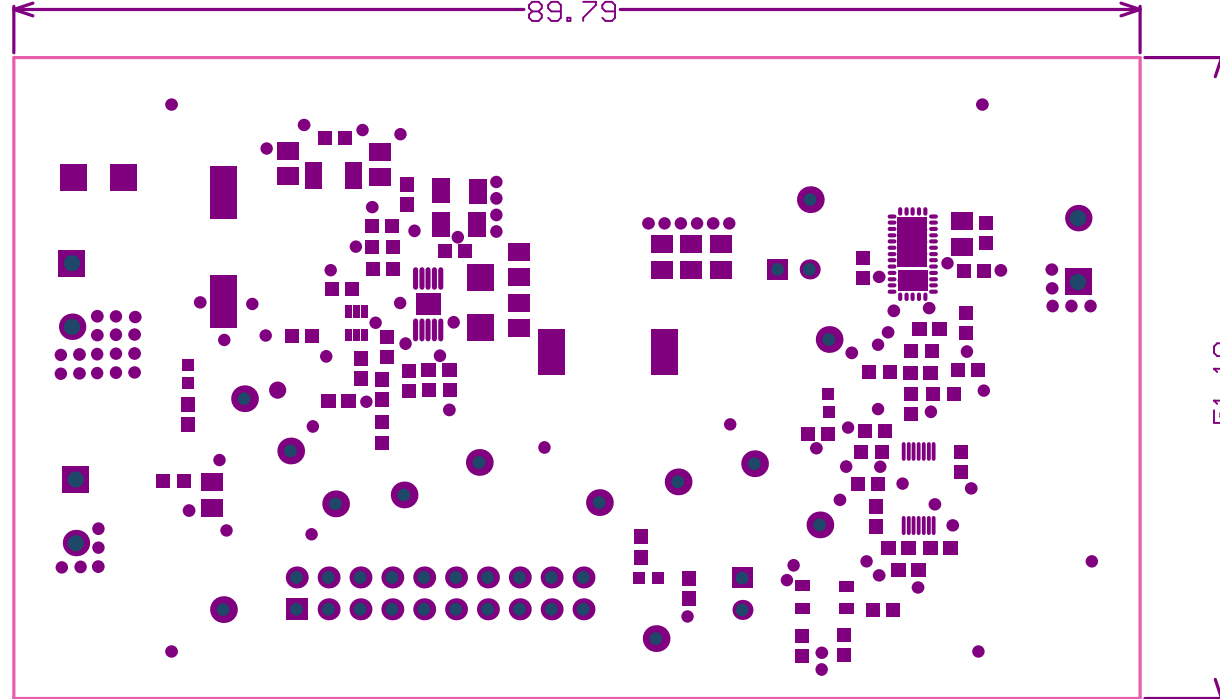
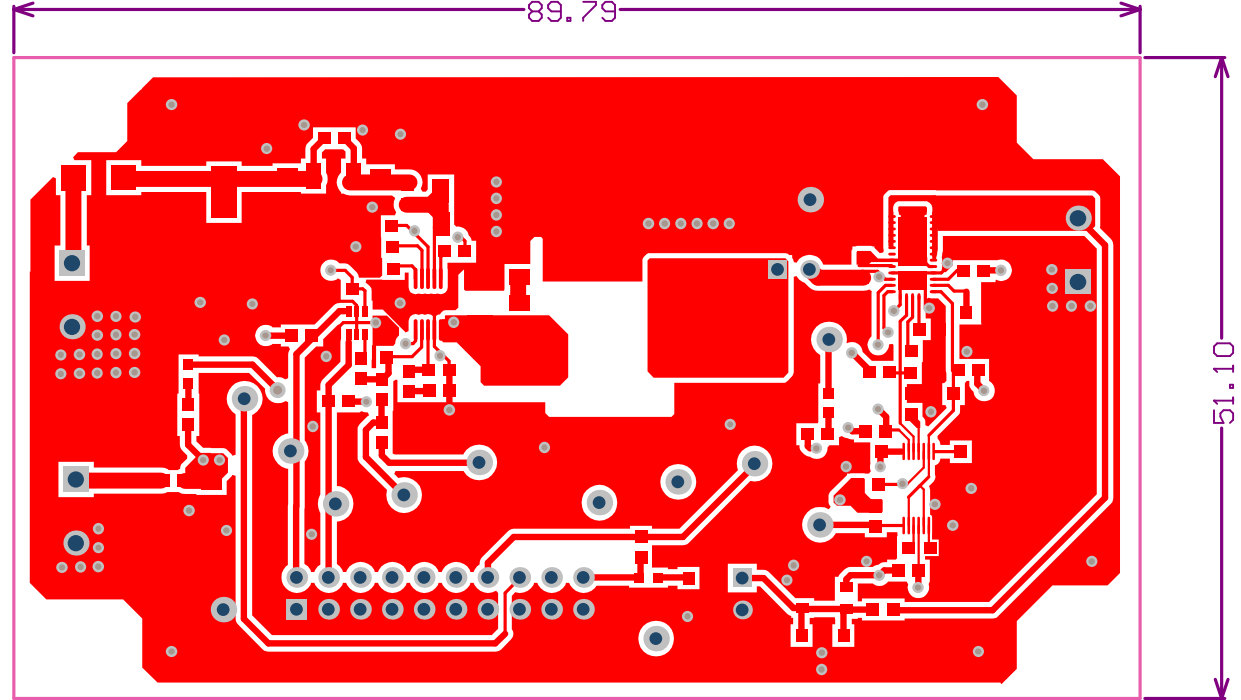


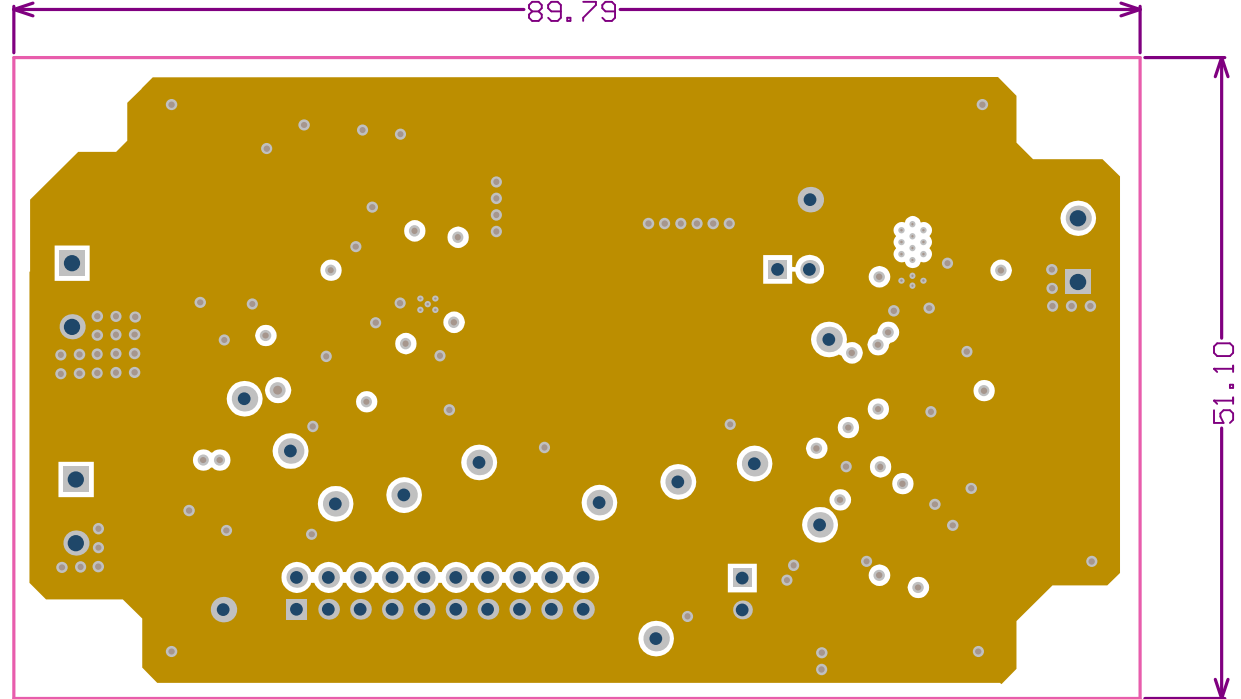
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00180	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = TopOverlay	GENERATED : 9/12/2014	5:11:33 PM	TEXAS INSTRUMENTS



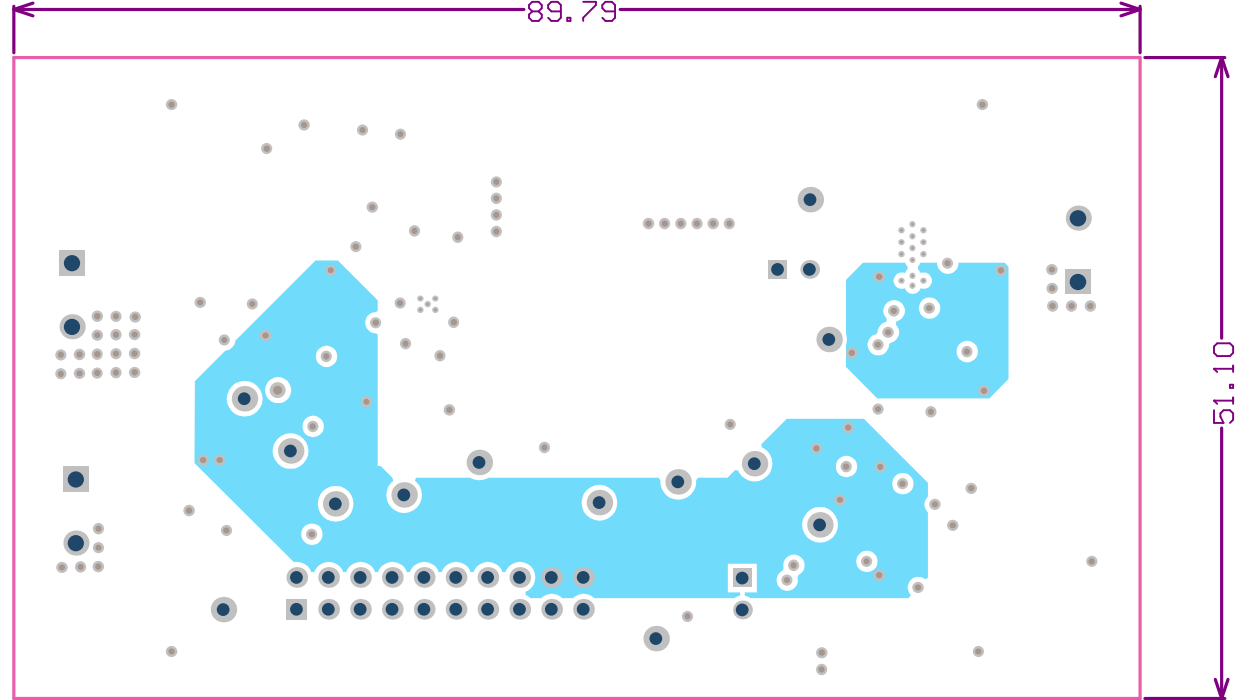
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00180	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =			
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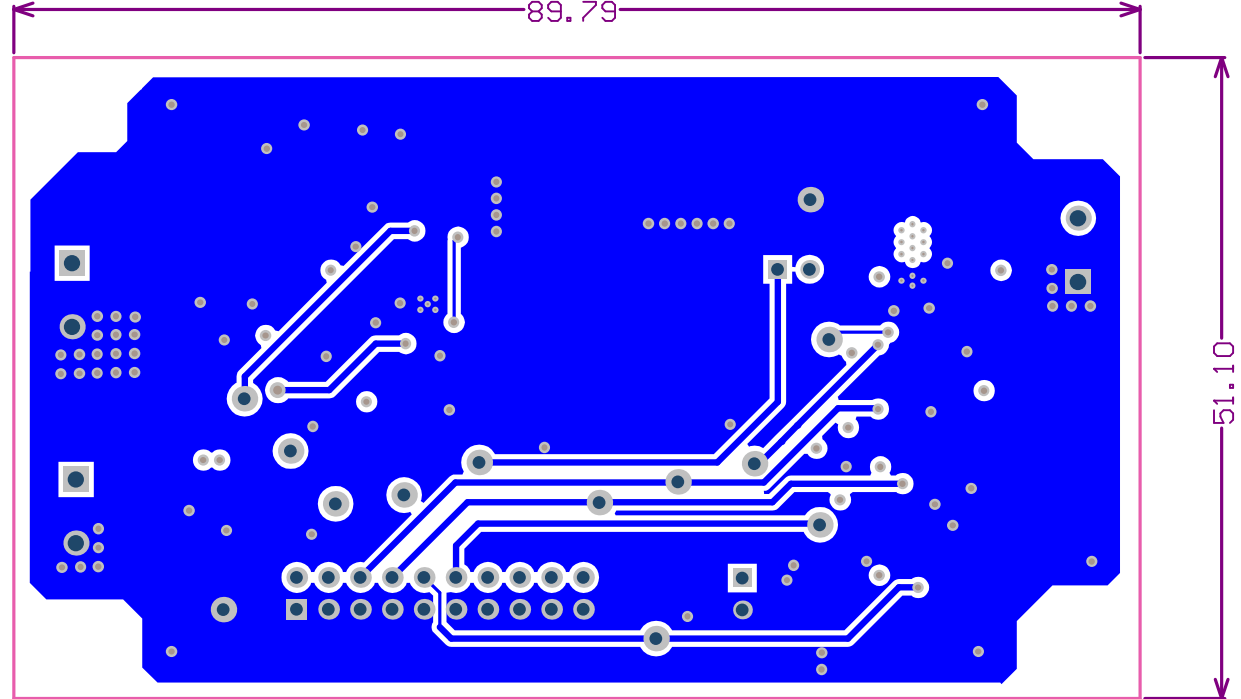
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00180	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = TopLayer	GENERATED : 9/12/2014 5:11:34 PM	TEXAS INSTRUMENTS	



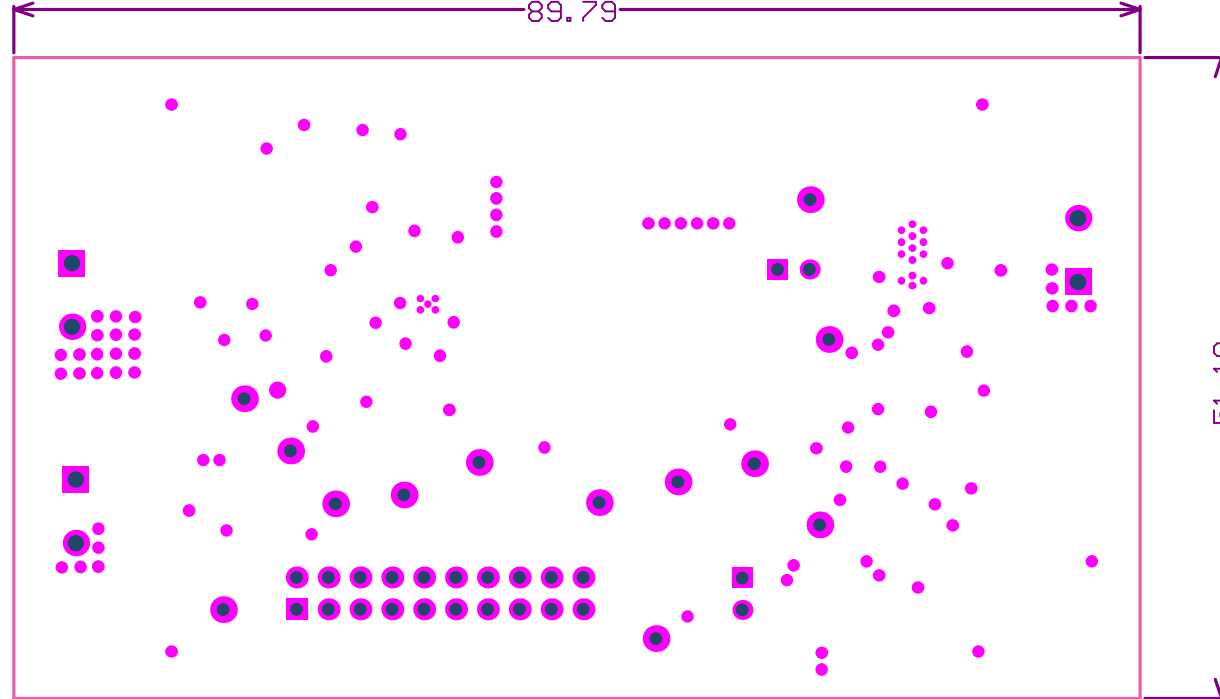
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00180	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = mid layer 1-GND			
PLOT NAME = Mid Layer 1 - GND	GENERATED : 9/12/2014 5:11:35 PM	TEXAS INSTRUMENTS	



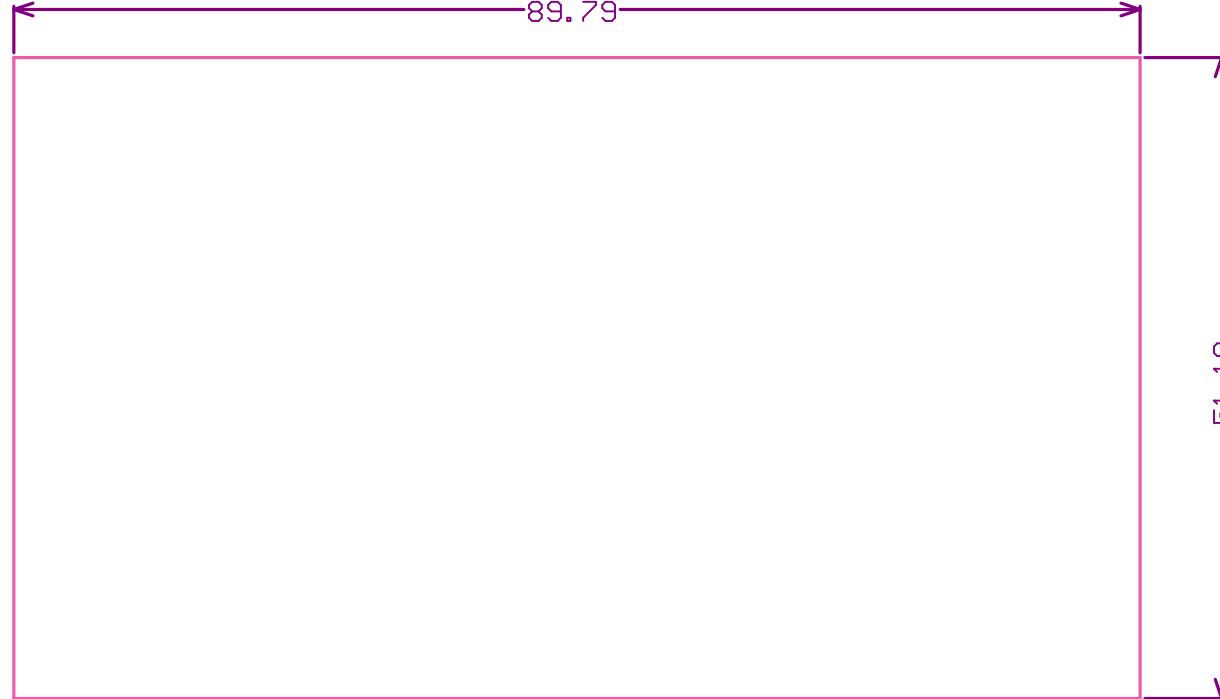
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00180	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = mid layer 2-VCC			
PLOT NAME = Mid Layer 2 - VCC	GENERATED : 9/12/2014 5:11:36 PM	TEXAS INSTRUMENTS	



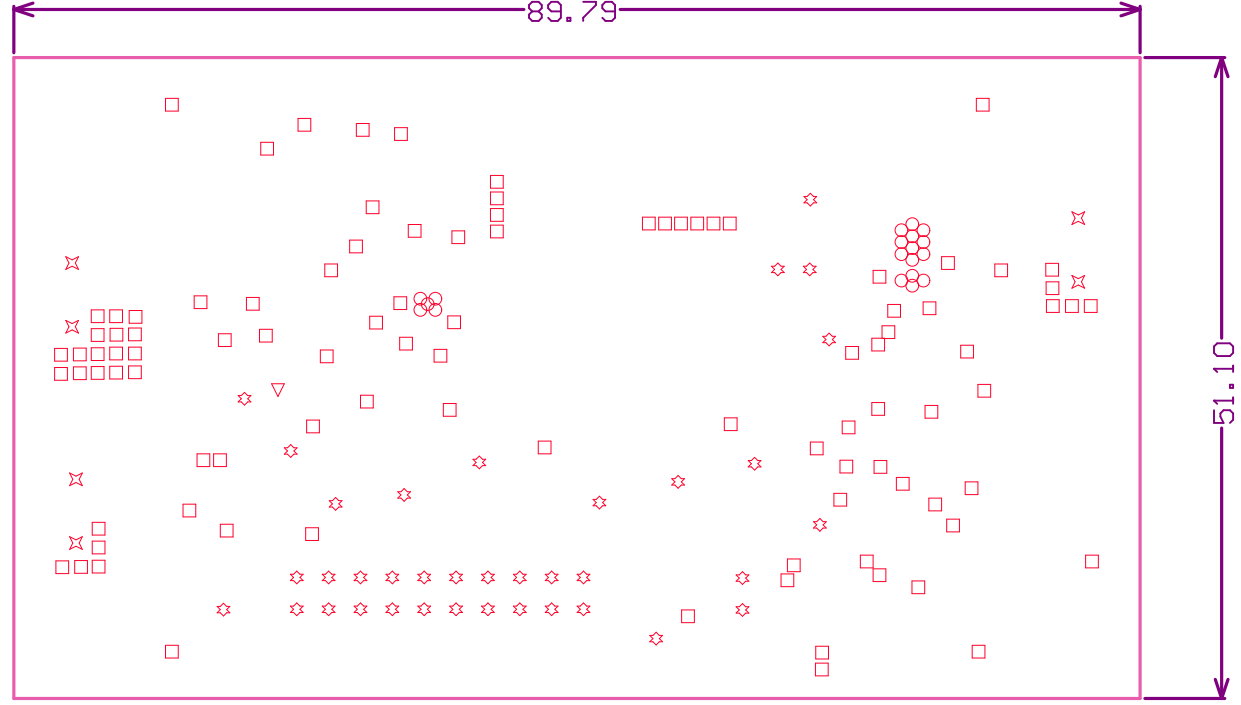
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00180	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 9/12/2014 5:11:36 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00180	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Bottom Solder Mask	GENERATED : 9/12/2014 5:11:37 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00180	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Bottom Overlay	GENERATED : 9/12/2014 5:11:37 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00180	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Drill Drawing	GENERATED : 9/12/2014	5:11:38 PM	TEXAS INSTRUMENTS

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